

SOT1003-1

plastic thermal enhanced very thin quad flat package; no leads; 25 terminals; body 5 x 5 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN25
Package type industry code	HVQFN25
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	9-6-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.9	-	5	5.1	mm
A	seated height	0.8	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	25	-	

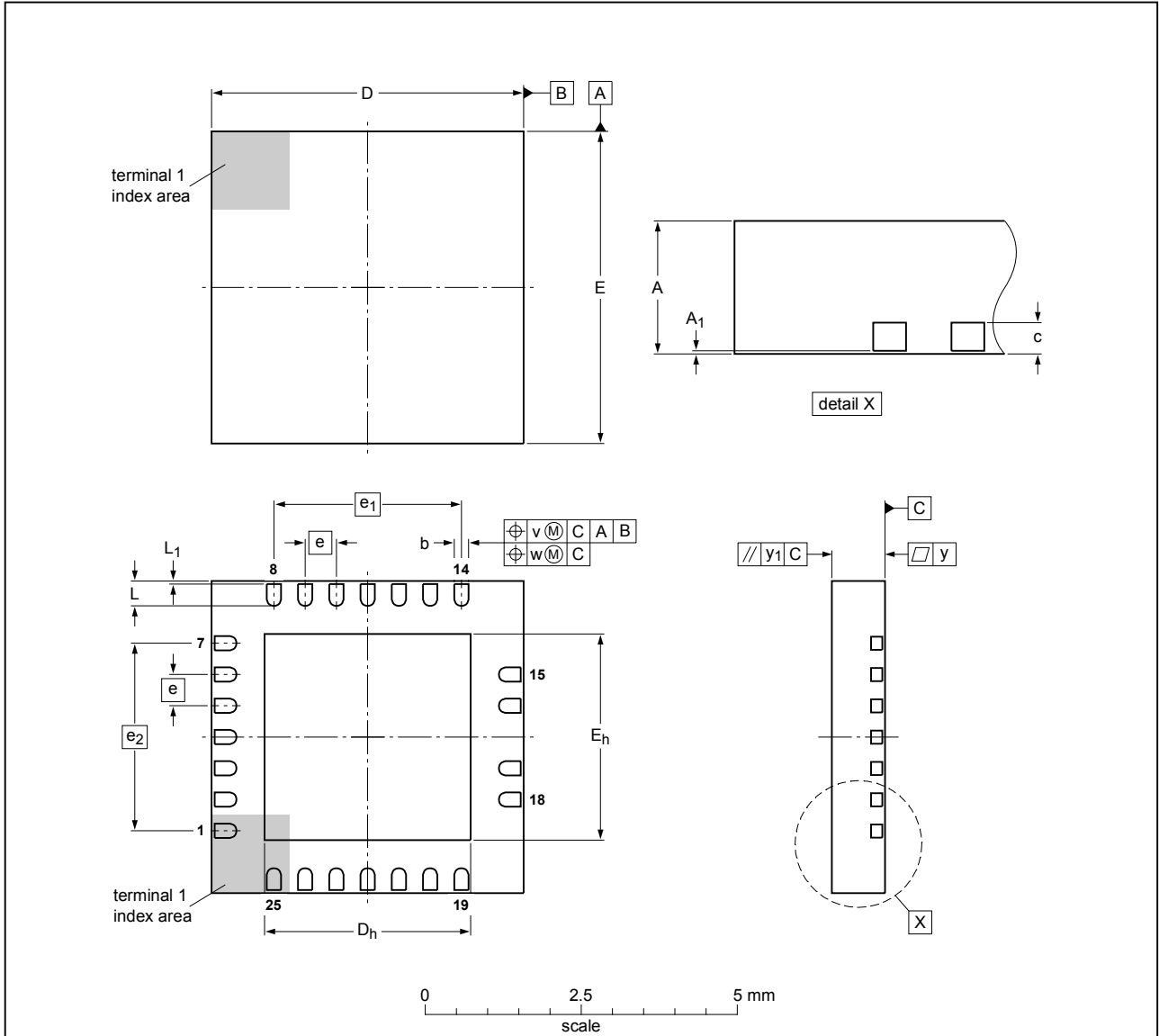


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2. Package outline

HVQFN25: plastic thermal enhanced very thin quad flat package; no leads; 25 terminals; body 5 x 5 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT		A	A ₁	b	c	D	D _h	E	E _h	e	e ₁	e ₂	L	L ₁	v	w	y	y ₁
mm	max	1.00	0.05	0.30	0.2	5.1	3.4	5.1	3.4	0.5	3	3	0.5	0.08	0.1	0.05	0.05	0.1
	nom	0.85	0.02	0.23	0.2	5.0	3.3	5.0	3.3	0.5	3	3	0.4	0.05	0.1	0.05	0.05	0.1
	min	0.80	0.00	0.18	0.2	4.9	3.2	4.9	3.2	0.5	3	3	0.3	0.03	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1003-1		MO-220	---			08-04-18 08-06-09

Fig. 1. Package outline HVQFN25 (SOT1003-1)

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3. Legal information

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